

Tzong-Lin Wu

List of Publications by Year in descending order

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253
papers

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citations

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254
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times ranked

1777
citing authors

#	ARTICLE	IF	CITATIONS
1	A Novel Wideband Common-Mode Suppression Filter for Gigahertz Differential Signals Using Coupled Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 848-855.	2.9	261
2	An Embedded Common-Mode Suppression Filter for GHz Differential Signals Using Periodic Defected Ground Plane. IEEE Microwave and Wireless Components Letters, 2008, 18, 248-250.	2.0	258
3	Electromagnetic bandgap power/ground planes for wideband suppression of ground bounce noise and radiated emission in high-speed circuits. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 2935-2942.	2.9	212
4	Overview of Power Integrity Solutions on Package and PCB: Decoupling and EBG Isolation. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 346-356.	1.4	181
5	Overview of Signal Integrity and EMC Design Technologies on PCB: Fundamentals and Latest Progress. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 624-638.	1.4	166
6	A novel power plane with super-wideband elimination of ground bounce noise on high speed circuits. IEEE Microwave and Wireless Components Letters, 2005, 15, 174-176.	2.0	147
7	A Broadband and Miniaturized Common-Mode Filter for Gigahertz Differential Signals Based on Negative-Permittivity Metamaterials. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 195-202.	2.9	143
8	A novel ultraflattened dispersion photonic Crystal fiber. IEEE Photonics Technology Letters, 2005, 17, 67-69.	1.3	115
9	Numerical and Experimental Investigation of Radiation Caused by the Switching Noise on the Partitioned DC Reference Planes of High Speed Digital PCB. IEEE Transactions on Electromagnetic Compatibility, 2004, 46, 33-45.	1.4	93
10	Analysis of propagation characteristics for an octagonal photonic crystal fiber (O-PCF). Optics Communications, 2006, 258, 170-176.	1.0	84
11	A novel power planes with low radiation and broadband suppression of ground bounce noise using photonic bandgap structures. IEEE Microwave and Wireless Components Letters, 2004, 14, 337-339.	2.0	81
12	A Novel 2.5-Dimensional Ultraminiaturized-Element Frequency Selective Surface. IEEE Transactions on Antennas and Propagation, 2014, 62, 3657-3663.	3.1	73
13	Radiation Suppression for Cable-Attached Packages Utilizing a Compact Embedded Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1696-1703.	1.4	69
14	A Magnetic-Field Resonant Probe With Enhanced Sensitivity for RF Interference Applications. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 991-998.	1.4	59
15	Synthesis Model and Design of a Common-Mode Bandstop Filter (CM-BSF) With an All-Pass Characteristic for High-Speed Differential Signals. IEEE Transactions on Microwave Theory and Techniques, 2014, 62, 1647-1656.	2.9	59
16	A Circular-Ring Miniaturized-Element Metasurface With Many Good Features for Frequency Selective Shielding Applications. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 365-374.	1.4	58
17	A New Broadband Common-Mode Noise Absorption Circuit for High-Speed Differential Digital Systems. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 1894-1901.	2.9	56
18	A Novel Power/Ground Layer Using Artificial Substrate EBG for Simultaneously Switching Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1164-1171.	2.9	54

#	ARTICLE	IF	CITATIONS
19	An Effective Via-Based Frequency Adjustment and Minimization Methodology for Single-Layered Frequency-Selective Surfaces. IEEE Transactions on Antennas and Propagation, 2015, 63, 1641-1649.	3.1	48
20	Theoretical demonstration of enhancement of light extraction of flip-chip GaN light-emitting diodes with photonic crystals. Applied Physics Letters, 2006, 89, 091116.	1.5	46
21	An Ultra-Compact Common-Mode Bandstop Filter With Modified-T Circuits in Integrated Passive Device (IPD) Process. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 3624-3631.	2.9	46
22	Design and Modeling of a Stopband-Enhanced EBG Structure Using Ground Surface Perturbation Lattice for Power/Ground Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 2047-2054.	2.9	44
23	A New Model for Through-Silicon Vias on 3-D IC Using Conformal Mapping Method. IEEE Microwave and Wireless Components Letters, 2012, 22, 303-305.	2.0	40
24	A photonic crystal power/ground layer for eliminating simultaneously switching noise in high-speed circuit. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 3398-3406.	2.9	39
25	Bandwidth Enhancement Based on Optimized Via Location for Multiple Vias EBG Power/Ground Planes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 332-341.	1.4	37
26	Bandwidth Enhancement of 4\$,imes,\$4 Butler Matrix Using Broadband Forward-Wave Directional Coupler and Phase Difference Compensation. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 4099-4109.	2.9	36
27	Anxiety levels in women undergoing prenatal maternal serum screening for Down syndrome: the effect of a fast reporting system by mobile phone short-message service. Prenatal Diagnosis, 2008, 28, 417-421.	1.1	34
28	Numerical modeling of weakly fused fiber-optic polarization beamsplitters. Part II: the three-dimensional electromagnetic model. Journal of Lightwave Technology, 1998, 16, 691-696.	2.7	32
29	A Compact and Embedded Balanced Bandpass Filter With Wideband Common-Mode Suppression on Wireless SiP. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1030-1038.	1.4	32
30	Design and Analysis of an Ultraminiaturized Frequency Selective Surface With Two Arbitrary Stopbands. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1447-1456.	1.4	32
31	A novel fabrication method for all-fiber, weakly fused, polarization beamsplitters. IEEE Photonics Technology Letters, 1995, 7, 786-788.	1.3	30
32	Modeling Noise Coupling Between Package and PCB Power/Ground Planes With an Efficient 2-D FDTD/Lumped Element Method. IEEE Transactions on Advanced Packaging, 2007, 30, 864-871.	1.7	29
33	A Novel Absorptive Common-Mode Filter for Cable Radiation Reduction. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 511-518.	1.4	29
34	Miniaturized Dual-Band FSS Suitable for Curved Surface Application. IEEE Antennas and Wireless Propagation Letters, 2020, 19, 2265-2269.	2.4	29
35	Photonic Crystal Fiber Analysis Through the Vector Boundary-Element Method: Effect of Elliptical Air Hole. IEEE Photonics Technology Letters, 2004, 16, 126-128.	1.3	28
36	Signal/Power Integrity Modeling of High-Speed Memory Modules Using Chip-Package-Board Coanalysis. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 381-391.	1.4	28

#	ARTICLE	IF	CITATIONS
37	An Ultracompact TSV-Based Common-Mode Filter (TSV-CMF) in Three-Dimensional Integrated Circuits (3-D ICs). IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 1128-1135.	1.4	28
38	Low-Cost and Low-Electromagnetic-Interference Packaging of Optical Transceiver Modules. Journal of Lightwave Technology, 2004, 22, 2177-2183.	2.7	27
39	Analytical Design of Via Lattice for Ground Planes Noise Suppression and Application on Embedded Planar EBG Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 21-30.	1.4	27
40	Effective electromagnetic shielding of plastic packaging in low-cost optical transceiver modules. Journal of Lightwave Technology, 2003, 21, 1536-1543.	2.7	26
41	A novel approach for the incorporation of arbitrary linear lumped network into FDTD method. IEEE Microwave and Wireless Components Letters, 2004, 14, 74-76.	2.0	26
42	Very Closely Located Dual-Band Frequency Selective Surfaces via Identical Resonant Elements. IEEE Antennas and Wireless Propagation Letters, 2015, 14, 414-417.	2.4	26
43	ABF-Based TSV Arrays With Improved Signal Integrity on 3-D IC/Interposers: Equivalent Models and Experiments. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1744-1753.	1.4	25
44	Model and Mechanism of Miniaturized and Stopband-Enhanced Interleaved EBG Structure for Power/Ground Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 159-167.	1.4	24
45	Analysis and Design Method of a Novel Absorptive Common-Mode Filter. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1826-1835.	2.9	23
46	A Novel and Compact Eight-Port Forward-Wave Directional Coupler With Arbitrary Coupling Level Design Using Four-Mode Control Technology. IEEE Transactions on Microwave Theory and Techniques, 2017, 65, 467-475.	2.9	22
47	Mitigation of Noise Coupling in Multilayer High-Speed PCB: State of the Art Modeling Methodology and EBG Technology. IEICE Transactions on Communications, 2010, E93-B, 1678-1689.	0.4	21
48	A Synthesized Method for Common-Mode Noise Suppression Filters With Specified Common-Mode and Differential Mode Response. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 893-902.	1.4	21
49	Coupling of the ground bounce noise to the signal trace with via transition in partitioned power bus of PCB. , 0, , .		20
50	Synthesized Method of Dual-Band Common-Mode Noise Absorption Circuits. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1392-1401.	2.9	20
51	An optimum approach for fabrication of low loss fused fiber couplers. Materials Chemistry and Physics, 2001, 69, 199-203.	2.0	19
52	A Novel Compact Forward-Wave Directional Coupler Design Using Periodical Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 1249-1257.	2.9	19
53	Novel crosstalk modeling for multiple through-silicon-vias (TSV) on 3-D IC: Experimental validation and application to Faraday cage design. , 2012, , .		19
54	Estimation Method for Statistical Eye Diagram in a Nonlinear Digital Channel. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 1655-1664.	1.4	19

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55	Compact Cascaded-Spiral-Patch EBG Structure for Broadband SSN Mitigation in WLAN Applications. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 2740-2748.	2.9	19
56	A Compact Loop-Slot Mode Combination Antenna for Ultra-Thin Tablet Computer With Metallic Bottom Cover. IEEE Antennas and Wireless Propagation Letters, 2014, 13, 746-749.	2.4	18
57	New Package Scheme of a 2.5-Gb/s Plastic Transceiver Module Employing Multiwall Nanotubes for Low Electromagnetic Interference. IEEE Journal of Selected Topics in Quantum Electronics, 2006, 12, 1025-1032.	1.9	17
58	A Novel Miniaturized Forward-Wave Directional Coupler With Periodical Mushroom-Shaped Ground Plane. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 2277-2283.	2.9	17
59	Design and Implementation of a Novel Hybrid Photonic Crystal Power/Ground Layer for Broadband Power Noise Suppression. IEEE Transactions on Advanced Packaging, 2010, 33, 206-211.	1.7	17
60	Balanced-to-Balanced and Balanced-to-Unbalanced Power Dividers With Ultra-Wideband Common-Mode Rejection and Absorption Based on Mode-Conversion Approach. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 306-316.	1.4	17
61	Novel Differential-Mode Equalizer With Broadband Common-Mode Filtering for Gb/s Differential-Signal Transmission. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1578-1587.	1.4	16
62	Ultracompact Via-Based Absorptive Frequency-Selective Surface for 5-GHz Wi-Fi With Passbands and High-Performance Stability. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 41-49.	1.4	16
63	Embedded power plane with ultra-wide stop-band for simultaneously switching noise on high-speed circuits. Electronics Letters, 2006, 42, 213.	0.5	15
64	A Power Bus With Multiple Via Ground Surface Perturbation Lattices for Broadband Noise Isolation: Modeling and Application in RF-SiP. IEEE Transactions on Advanced Packaging, 2010, 33, 582-591.	1.7	15
65	A Broadband Forward-Wave Directional Coupler Using Periodic Y-Shaped Ground Via Structures With Arbitrary Coupling Levels. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 38-47.	2.9	15
66	An Electromagnetic Bandgap Structure Integrated With RF LNA Using Integrated Fan-Out Wafer-Level Package for Gigahertz Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 5482-5490.	2.9	15
67	A Resistor-Free Absorptive Common-Mode Filter Using Gap-Coupled Resonator. IEEE Microwave and Wireless Components Letters, 2018, 28, 885-887.	2.0	15
68	Electromagnetic shielding of plastic packaging in low-cost laser modules. Electronics Letters, 2000, 36, 118.	0.5	14
69	A Novel Time Domain Method to Extract Equivalent Circuit Model of Patterned Ground Structures. IEEE Microwave and Wireless Components Letters, 2010, 20, 486-488.	2.0	14
70	Mold-based compartment shielding to mitigate the intra-system coupled noise on SiP modules. , 2011, , .		14
71	A Rigorous Proof on the Radiation Resistance in Generalized PEEC Model. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 4091-4097.	2.9	14
72	Novel Absorptive Balanced Bandpass Filters Using Resistive Loaded Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 745-753.	1.4	14

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73	Rigorous analysis of form birefringence of weakly fused fiber-optic couplers. Journal of Lightwave Technology, 1995, 13, 687-691.	2.7	13
74	A Novel Dual-Function Circuit Combining High-Speed Differential Equalizer and Common-Mode Filter With an Additional Zero. IEEE Microwave and Wireless Components Letters, 2014, 24, 617-619.	2.0	13
75	A High-Performance Common-Mode Noise Absorption Circuit Based on Phase Modification Technique. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 4394-4403.	2.9	13
76	A Novel Ground Resonator Technique to Reduce Common-Mode Radiation on Slot-Crossing Differential Signals. IEEE Microwave and Wireless Components Letters, 2010, 20, 660-662.	2.0	12
77	Conformal shielding investigation for SiP modules. , 2010, , .		12
78	A novel TSV model considering nonlinear MOS effect for transient analysis. , 2012, , .		12
79	An Equation-Based Circuit Model and Its Generation Tool for 3-D IC Power Delivery Networks With an Emphasis on Coupling Effect. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1062-1070.	1.4	12
80	A Novel Circuit Architecture of Bidirectional Common-Mode Noise Absorption Circuit. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 1476-1486.	2.9	12
81	Investigation of signal quality and radiated emission of microstrip line on imperfect ground plane: FDTD analysis and measurement. , 0, , .		11
82	A novel systematic approach for equivalent model extraction of embedded high-speed interconnects in time domain. IEEE Transactions on Electromagnetic Compatibility, 2003, 45, 493-501.	1.4	11
83	Prediction of near-field shielding effectiveness for conformal-shielded SiP and measurement with magnetic probe. , 2015, , .		11
84	A Resistor-Free N -Way Power Divider With Simultaneous Output Matching and Isolation. IEEE Microwave and Wireless Components Letters, 2019, 29, 523-525.	2.0	11
85	A Novel Compact Single-Stage Absorption Common-Mode Filter. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 111-118.	1.4	11
86	Rigorous analysis of form birefringence of fused fibre couplers. Electronics Letters, 1994, 30, 998-999.	0.5	10
87	The bridging effect of the isolation moat on the EMI caused by ground bounce noise between power/ground planes of PCB. , 0, , .		10
88	Numerical and experimental investigation of noise coupling perturbed by ESD currents on printed circuit boards. , 0, , .		10
89	A Novel Approach for Calculating the Dispersions of Photonic Crystal Fibers. IEEE Photonics Technology Letters, 2004, 16, 1492-1494.	1.3	10
90	Low slow-wave effect and crosstalk for low-cost ABF-coated TSVs in 3-D IC interposer. , 2012, , .		10

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91	The effect of various skew compensation strategies on mode conversion and radiation from high-speed connectors. , 2013, , .		10
92	Broadband Eight-Port Forward-Wave Directional Couplers and Four-Way Differential Phase Shifter. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 2161-2169.	2.9	10
93	Design of a Broadband Common-Mode Filter With Four Transmission Zeros. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1052-1060.	1.4	10
94	Three-dimensional electromagnetic modeling of fiber-core effects on the coupling characteristics of weakly fused tapered fiber-optic couplers. Journal of Lightwave Technology, 2000, 18, 1024-1030.	2.7	9
95	An efficient approach for calculating the dispersions of photonic-crystal fibers: design of the nearly zero ultra-flattened dispersion. Journal of Lightwave Technology, 2005, 23, 2055-2061.	2.7	9
96	A Time-Domain Approach for Extracting Broadband Macro- π Models of Differential Via Holes. IEEE Transactions on Advanced Packaging, 2006, 29, 789-797.	1.7	9
97	Power integrity chip-package-PCB co-simulation for I/O interface of DDR3 high-speed memory. , 2008, , .		9
98	A metamaterial-typed differential transmission line with broadband common-mode suppression. , 2009, , .		9
99	A GHz common-mode filter using negative permittivity metamaterial on low temperature co-fire ceramic (LTCC) substrate. , 2009, , .		9
100	A novel common mode choke and its application for 5 Gbps USB 3.0. , 2011, , .		9
101	Dual-band WLAN MIMO antenna with a decoupling element for full-metallic bottom cover tablet computer applications. Microwave and Optical Technology Letters, 2018, 60, 1245-1251.	0.9	9
102	Design and Modeling of a Compact Partially Transmissible Resistor-Free Absorptive Frequency Selective Surface for Wi-Fi Applications. IEEE Transactions on Antennas and Propagation, 2019, 67, 1306-1311.	3.1	9
103	Balanced Bandpass Filter With Common-Mode Reflectionless Feature by Terminated Coupled Lines. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 1090-1097.	1.4	9
104	An electromagnetic crystal power substrate with efficient suppression of power/ground plane noise on high-speed circuits. IEEE Microwave and Wireless Components Letters, 2006, 16, 413-415.	2.0	8
105	Signal/power integrity design strategy for low-cost package of high-speed memory I/O interfaces. , 2009, , .		8
106	3D simulation of substrate noise coupling from Through Silicon Via (TSV) and noise isolation methods. , 2012, , .		8
107	EBG-Based Grid-Type PDN on Interposer for SSN Mitigation in Mixed-Signal System-in-Package. IEEE Microwave and Wireless Components Letters, 2017, 27, 1053-1055.	2.0	8
108	The effect of test system impedance on measurements of ground bounce in printed circuit boards. IEEE Transactions on Electromagnetic Compatibility, 2001, 43, 600-607.	1.4	7

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109	Analysis of radiation caused by SSN and transmission line by combining the equivalent circuits of active IC into FDTD. , 0, , .		7
110	A Novel EBG Power Plane with Stopband Enhancement using Artificial Substrate. , 2007, , .		7
111	Chip-package-board co-design - a DDR3 system design example from circuit designers’ perspective. , 2008, , .		7
112	Eye prediction of digital driver with power distribution network noise. , 2012, , .		7
113	Statistical eye diagram prediction for a 8b10b-coded channel using pulse response. , 2014, , .		7
114	Modeling and Analysis of Bandwidth-Enhanced Multilayer 1-D EBG With Bandgap Aggregation for Power Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 858-867.	1.4	7
115	Investigation of signal integrity issues in multi-path electrostatic discharge protection device. , 2015, , .		7
116	Signal/Power Integrity Co-Simulation of DDR3 Memory Module. , 2018, , .		7
117	Direct Simulation of the Full-Wave Partial Element Equivalent Circuit Using Standard SPICE [Application Notes]. IEEE Microwave Magazine, 2019, 20, 22-34.	0.7	7
118	A new frequency selective surface power plane with broad band rejection for simultaneous switching noise on high-speed printed circuit boards. , 0, , .		6
119	High electromagnetic shielding of plastic package for 2.5-Gb/s optical transceiver modules. IEEE Transactions on Advanced Packaging, 2005, 28, 89-95.	1.7	6
120	Suppression of Common-Mode Radiation and Mode Conversion for Slot-Crossing GHz Differential Signals Using Novel Grounded Resonators. IEEE Transactions on Electromagnetic Compatibility, 2011, 53, 429-436.	1.4	6
121	Radio-frequency interference mitigation strategies for high-speed connectors. , 2013, , .		6
122	A Novel Compact Balun Using a Weakly Coupled Line With Grounded Resonator. IEEE Microwave and Wireless Components Letters, 2014, 24, 763-765.	2.0	6
123	Novel absorptive design of common-mode filter at desired frequency band. , 2016, , .		6
124	Promoting Effective Education in Electromagnetics: Taiwan's School of Accessible and Visualized Electromagnetics Formed [Education Corner]. IEEE Antennas and Propagation Magazine, 2016, 58, 99-129.	1.2	6
125	Investigation of the Radiated Emissions From High-Speed/High-Density Connectors. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 220-230.	1.4	6
126	A Fully Integrated Arbitrary Power Divider on Printed Circuit Board by a Novel SMD-Resistor-Free Isolation Network. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1889-1901.	1.4	6

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127	Accurate coupling coefficients for fiber couplers with weakly fused cross sections. Applied Optics, 1995, 34, 6168.	2.1	5
128	A vector power coupling model for analyzing polarization-dependent loss of equilateral triangular 3Å–3 weakly fused fiber couplers. Optics Communications, 2003, 224, 81-88.	1.0	5
129	A novel time-domain method for synthesizing broadband macro-/spl pi/ models of differential via. IEEE Microwave and Wireless Components Letters, 2005, 15, 378-380.	2.0	5
130	A Broadband Chip-Level Power-Bus Model Feasible for Power Integrity Chip-Package Codesign in High-Speed Memory Circuits. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 235-239.	1.4	5
131	Parallel-plate noise suppression using a ground surface perturbation lattice (GSPL) structure. , 2010, , .		5
132	A Miniaturized and Broadband Balun Using Artificial Coupled Line With Imaginary Even-Mode Impedance. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 2233-2240.	2.9	5
133	Accuracy-improved through-silicon-via model using conformal mapping technique. , 2011, , .		5
134	A Branched Reflector Technique to Reduce Crosstalk Between Slot-Crossing Signal Lines. IEEE Microwave and Wireless Components Letters, 2012, 22, 342-344.	2.0	5
135	Compact TSV-based wideband bandpass filters on 3-D IC. , 2013, , .		5
136	Miniaturized and bandwidth-enhanced multilayer 1-D EBG structure for power noise suppression. , 2014, , .		5
137	Tri-section quarter wavelength resonator common mode filter. , 2015, , .		5
138	Balanced bandpass filter with reflectionless common-mode suppression. , 2016, , .		5
139	An Accurate and Fast Substrate Noise Prediction Method With Octagonal TSV Model for 3-D ICs. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 1549-1557.	1.4	5
140	Codesign of Electrostatic Discharge Protection Device and Common Mode Suppression Circuit on Printed Circuit Board. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1095-1101.	1.4	5
141	Wideband Reconfigurable Power Divider/Combiner in 40-nm CMOS for 5G mmW Beamforming System. IEEE Transactions on Microwave Theory and Techniques, 2022, 70, 1410-1422.	2.9	5
142	Vectorial analysis of fiber-core effects in weakly fused couplers. IEEE Photonics Technology Letters, 1997, 9, 218-219.	1.3	4
143	Characterizing package/PCB PDN interactions from a full-wave finite-difference formulation. , 2006, , .		4
144	The effects on SI and EMI for differential coupled microstrip lines over LPC-EBG power/ground planes. , 2008, , .		4

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145	Impact of Photonic Crystal Power/Ground Layer density on power integrity performance of high-speed power buses. , 2009, , .		4
146	Compact hybrid open stub EBG structure for power noise suppression in WLAN band. , 2015, , .		4
147	Compact wideband balanced filter for eliminating radio-frequency interference on differentially-fed antennas. , 2015, , .		4
148	Beamforming broadside antenna array for 60-GHz technology. , 2016, , .		4
149	EMI-reduction coding based on 8b/10b. , 2017, , .		4
150	A mm-Wave Low-Loss Transition from Microstrip Line to Air-Filled Substrate Integrated Waveguide on Printed Circuit Board Technology. , 2019, , .		4
151	Significant Crosstalk Reduction in High-Density Hollow Dielectric Waveguides by Photonic Crystal Fence. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 1316-1326.	2.9	4
152	Extraction of Complex Permittivity of Dielectrics on Package from W-band to D-band. , 2021, , .		4
153	Extremely Low-Loss Planar Transition From Hollow Dielectric Waveguide to Printed Circuit Board for Millimeter-Wave Interconnect. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 4010-4020.	2.9	4
154	A Compact Symmetrical Single-Cell Bidirectional Absorption Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 655-664.	1.4	4
155	Vectorial analysis for polarization effect of wavelength-flattened fiber-optic couplers. Microwave and Optical Technology Letters, 1999, 23, 12-16.	0.9	3
156	A Novel Time-Domain Algorithm for Synthesizing Broadband Macromodels of Coupled Interconnects. IEEE Transactions on Advanced Packaging, 2004, 27, 224-232.	1.7	3
157	Rigorous Analysis of Polarization-Dependence Loss (PDL) for Equilateral \times Fused Fiber Couplers. IEEE Photonics Technology Letters, 2004, 16, 165-167.	1.3	3
158	A novel stopband-enhanced EBG planes using an Embedded Slow-wave Structure in Low-cost RF-SiP. , 2008, , .		3
159	A novel broadband common-mode filter for high-speed differential signals. , 2008, , .		3
160	An ultra compact common-mode filter for RF Interference control in 3G wireless communication systems. , 2010, , .		3
161	A new bandstop filter using artificial defected ground structures with compact size and low radiation. , 2010, , .		3
162	Evaluation of magnetic field from varied permutation power transmission line at high technology nano-Fab. , 2011, , .		3

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163	Suppression of RF interference using balanced filter in communication system. , 2011, , .		3
164	A physics-based model of on-chip decoupling capacitor for accurate power integrity analysis. , 2011, , .		3
165	Analysis and design of GHz power noise isolation using 45° rotated photonic crystal fence. , 2011, , .		3
166	Transmission-line based modeling for conformal shielding in advance system-in-package (SiP). , 2015, , .		3
167	A compact dual-band common-mode filtering component for EMC in wireless communication. , 2015, , .		3
168	Balanced bandpass filter with intrinsic common mode suppression using slot coupled lines and microstrip loading lines. , 2016, , .		3
169	E-shape resonator dualband common mode filter. , 2016, , .		3
170	A balanced-to-balanced power divider with common-mode noise absorption. , 2016, , .		3
171	An eye diagram improvement method using simulation annealing algorithm. , 2018, , .		3
172	Poles and Stability of Full-Wave PEEC. IEEE Transactions on Antennas and Propagation, 2021, 69, 950-961.	3.1	3
173	All-fiber Brewster windows made with extremely weakly fused asymmetric coupler. IEEE Photonics Technology Letters, 1995, 7, 1054-1056.	1.3	2
174	An efficient numerical approach, for determining the dispersion characteristics of dual-mode elliptical-core optical fibers. Journal of Lightwave Technology, 1995, 13, 1926-1934.	2.7	2
175	Electromagnetic shielding of plastic packaging in cost-effective optical transceiver modules. , 0, , .		2
176	A low-cost plastic package for 2.5Gbps optical transceiver module with high electromagnetic shielding. , 0, , .		2
177	A novel HU-shaped common-mode filter for GHz differential signals. , 2008, , .		2
178	A new common-mode EMI suppression technique for GHz differential signals crossing slotted reference planes. , 2010, , .		2
179	A stopband enhanced EBG power/ground plane based on via location design. , 2010, , .		2
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